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Datasheet of SN74ALS1244AN - IC BUFF/DVR TRI-ST DUAL 20DIP

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**SN54ALS1244A, SN74ALS1244A  
OCTAL BUFFERS AND DRIVERS  
WITH 3-STATE OUTPUTS**

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- Low-Power Versions of 'ALS244 Series
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- pnp Inputs Reduce dc Loading
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

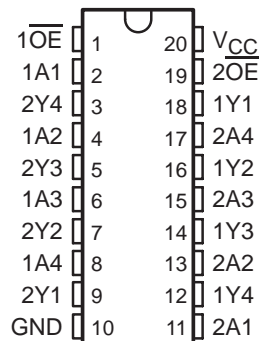
**description**

These octal buffers and drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

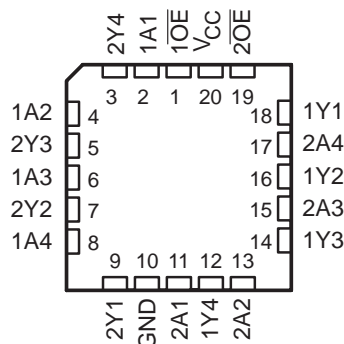
Taken together with the SN74ALS1240, these devices provide the choice of inverting and noninverting outputs.

The SN54ALS1244A is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS1244A is characterized for operation from 0°C to 70°C.

SN54ALS1244A . . . J PACKAGE  
SN74ALS1244A . . . DW OR N PACKAGE  
(TOP VIEW)



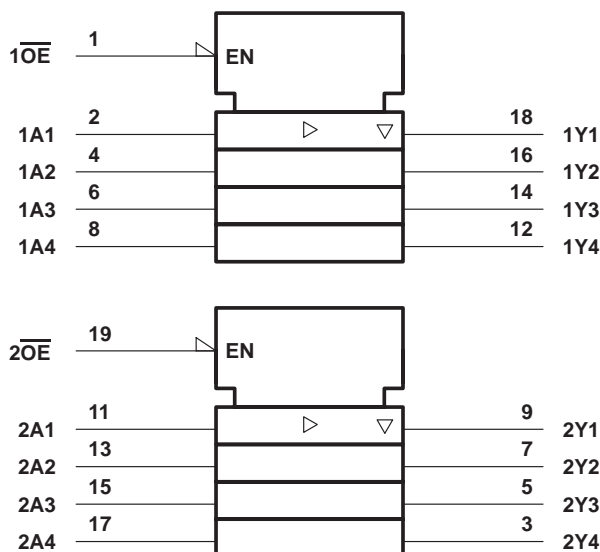
SN54ALS1244A . . . FK PACKAGE  
(TOP VIEW)



**SN54ALS1244A, SN74ALS1244A**  
**OCTAL BUFFERS AND DRIVERS**  
**WITH 3-STATE OUTPUTS**

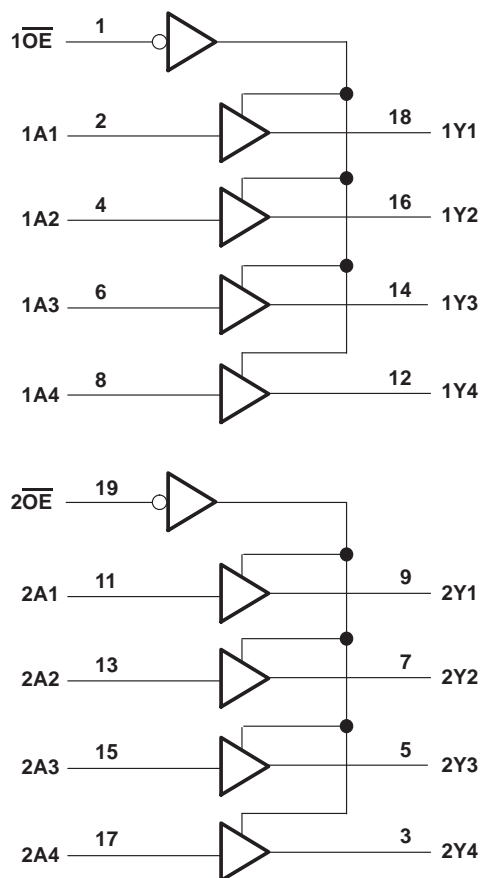
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**logic symbol†**



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

**logic diagram (positive logic)**



**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡**

Supply voltage, $V_{CC}$ .....	7 V
Input voltage, $V_I$ .....	7 V
Voltage applied to a disabled 3-state output .....	5.5 V
Operating free-air temperature range, $T_A$ : SN54ALS1244A .....	-55°C to 125°C
SN74ALS1244A .....	0°C to 70°C
Storage temperature range .....	-65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## SN54ALS1244A, SN74ALS1244A OCTAL BUFFERS AND DRIVERS WITH 3-STATE OUTPUTS

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### recommended operating conditions

		SN54ALS1244A			SN74ALS1244A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V <sub>IH</sub>	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage				0.7			V
I <sub>OH</sub>	High-level output current				-12			mA
I <sub>OL</sub>	Low-level output current				8			mA
T <sub>A</sub>	Operating free-air temperature	-55			125			°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54ALS1244A		SN74ALS1244A		UNIT
		MIN	TYP†	MAX	MIN	
V <sub>IK</sub>	V <sub>CC</sub> = 4.5 V, I <sub>I</sub> = -18 mA			-1.5		V
V <sub>OH</sub>	V <sub>CC</sub> = 4.5 V to 5.5 V, I <sub>OH</sub> = -0.4 mA	V <sub>CC</sub> - 2		V <sub>CC</sub> - 2		V
	V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -3 mA		2.4 3.2		
		I <sub>OH</sub> = -12 mA		2		
		I <sub>OH</sub> = -15 mA		2		
V <sub>OL</sub>	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 8 mA		0.25 0.4		V
		I <sub>OL</sub> = 16 mA		0.35 0.5		
I <sub>OZH</sub>	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 2.7 V			20		μA
I <sub>OZL</sub>	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 0.4 V			-20		μA
I <sub>I</sub>	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 7 V			0.1		mA
I <sub>IH</sub>	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 2.7 V			20		μA
I <sub>IL</sub>	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 0.4 V			-0.1		mA
I <sub>O‡</sub>	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 2.25 V	-20		-112		mA
I <sub>CC</sub>	V <sub>CC</sub> = 5.5 V	Outputs high		6 15		mA
		Outputs low		10 20		
		Outputs disabled		11 25		

† All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I<sub>OS</sub>.

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**switching characteristics (see Figure 1)**

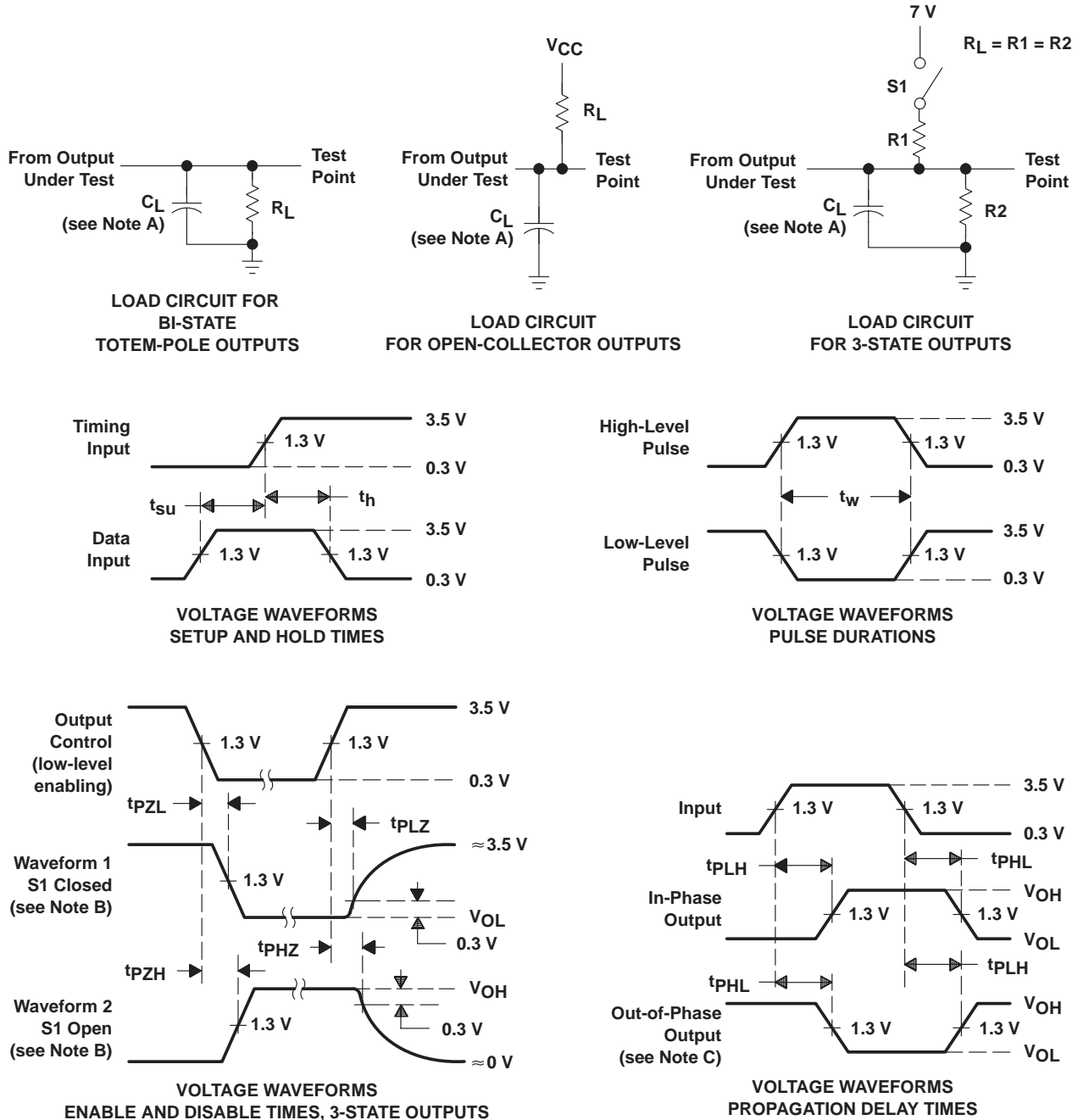
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T <sub>A</sub> = MIN to MAX†				UNIT
			SN54ALS1244A		SN74ALS1244A		
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A	Y	3	21	3	14	ns
t <sub>PHL</sub>			3	16	3	14	
t <sub>PZH</sub>	$\overline{OE}$	Y	6	28	6	22	ns
t <sub>PZL</sub>			6	26	6	22	
t <sub>PHZ</sub>	$\overline{OE}$	Y	2	15	2	13	ns
t <sub>PLZ</sub>			3	25	3	16	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

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**PARAMETER MEASUREMENT INFORMATION  
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES**



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.  
 D. All input pulses have the following characteristics:  $PRR \leq 1$  MHz,  $t_r = t_f = 2$  ns, duty cycle = 50%.  
 E. The outputs are measured one at a time with one transition per measurement.

**Figure 1. Load Circuits and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8873801RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8873801RA SNJ54ALS1244AJ	
SN74ALS1244AN	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70	SN74ALS1244AN	
SNJ54ALS1244AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8873801RA SNJ54ALS1244AJ	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54ALS1244A, SN74ALS1244A :**

- Catalog: [SN74ALS1244A](#)
- Military: [SN54ALS1244A](#)

**NOTE: Qualified Version Definitions:**

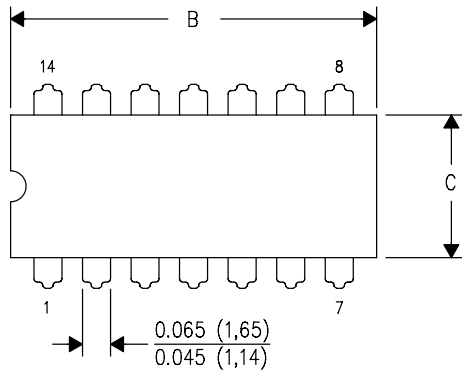
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications



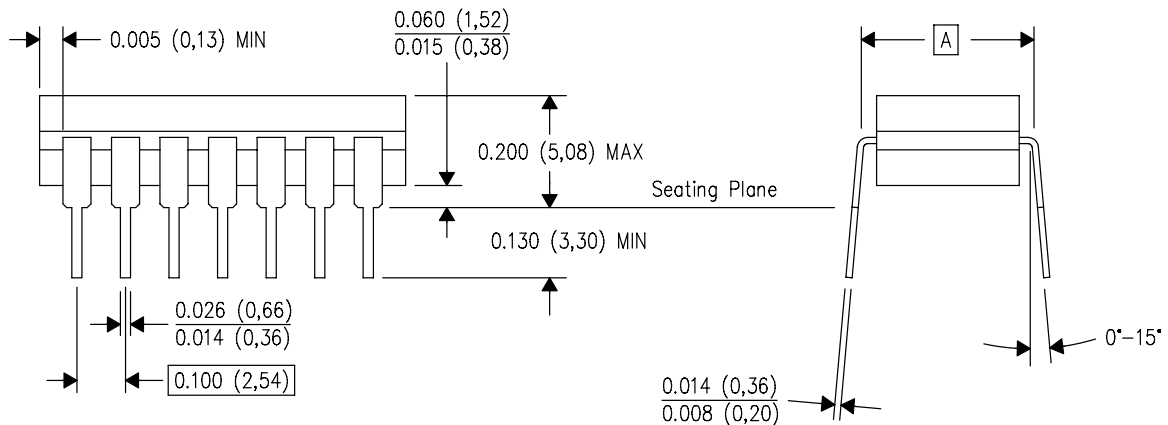
J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



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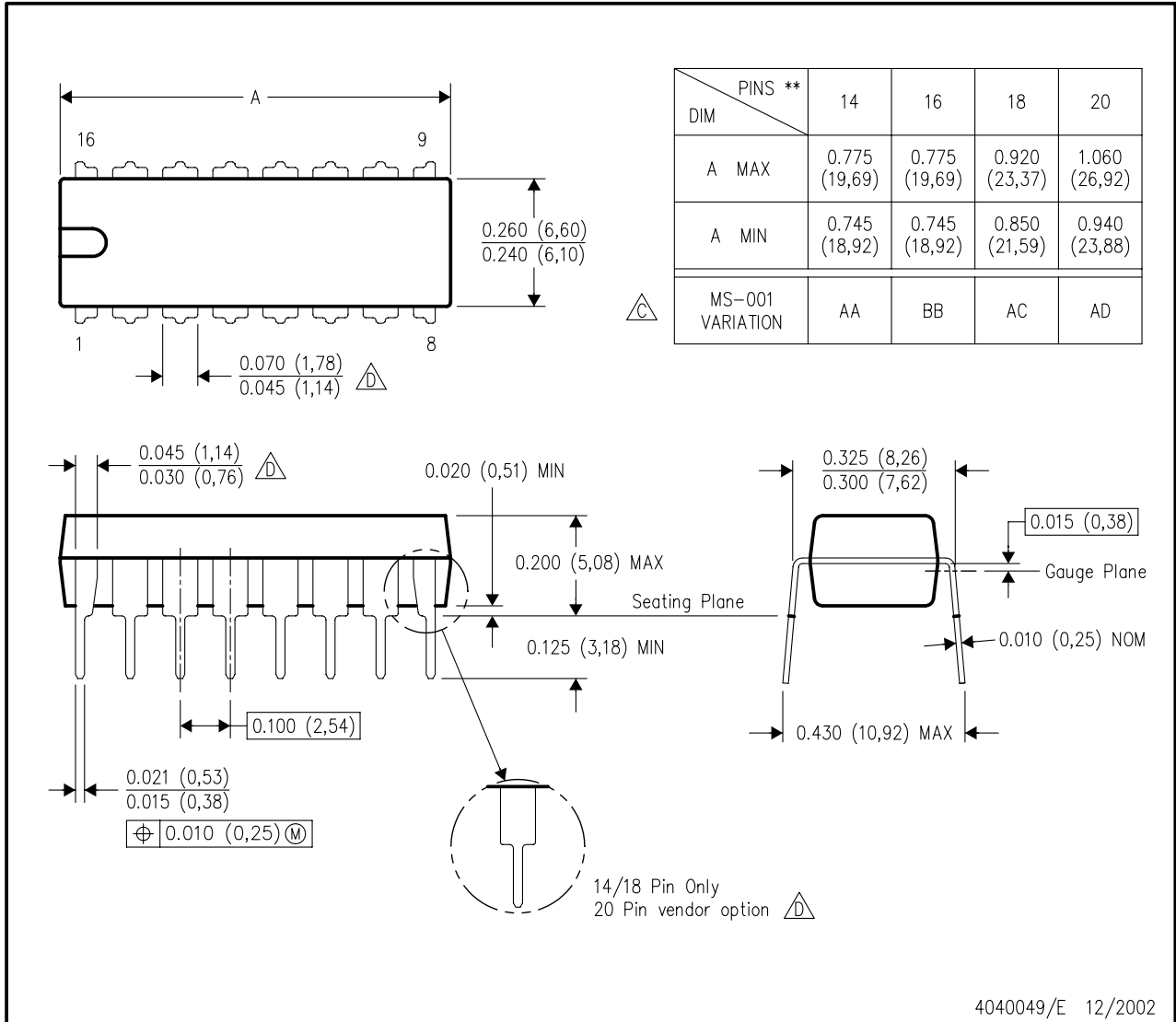
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

**MECHANICAL DATA**

**N (R-PDIP-T\*\*)**

16 PINS SHOWN

**PLASTIC DUAL-IN-LINE PACKAGE**



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

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